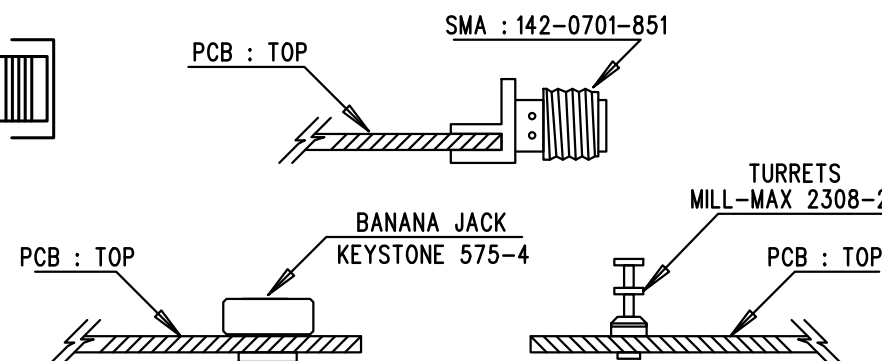


REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	JOHN C.	06-07-11

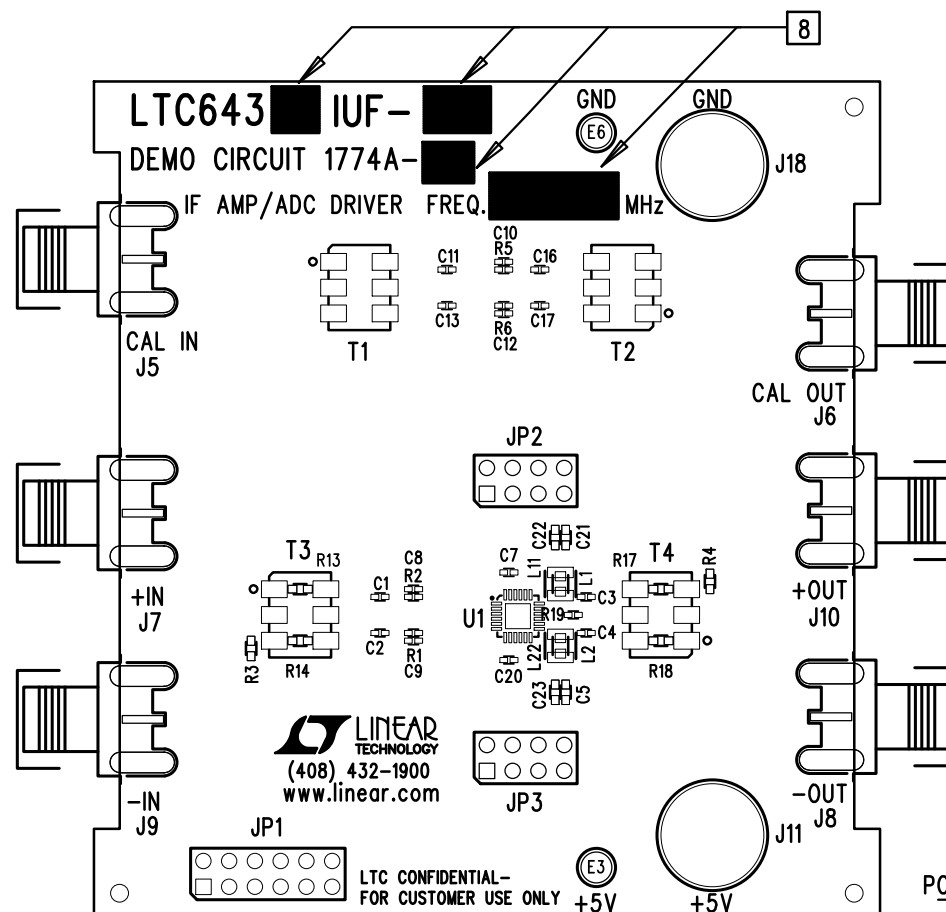
NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. NO SHUNT.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL SMA CONNECTORS, BANANA JACK, AND TURRETS AS SHOWN BELOW:



8. MARK EACH LTC PART NUMBER, FREQ., AND ASSEMBLY TYPE WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY	U1	FREQ.
-A	LTC6430IUF-15	100-300 MHz
-B	LTC6430IUF-15	400-1000 MHz
-C	LTC6431IUF-15	100-1200 MHz



APPROVALS

PCB DES.	KIM T.
APP ENG.	JOHN C.



1630 MCCARTHY BLVD
MILPITAS, CA 95035
PH: (408)432-1900
www.linear.com
LTC CONFIDENTIAL-FOR CUSTOMER USE ONLY

TITLE: TOP ASSEMBLY DRAWING

IF AMP/ADC DRIVER

SIZE N/A	IC NO. LTC643XIUF FAMILY DEMO CIRCUIT 1774A	REV. 2
-------------	---	-----------

SCALE = NONE

FILENAME: DC1774A-2.PCB

SHT 1 OF 2